

AL series Aluminum base copper clad laminate

Class	Type	Features
Aluminum base copper clad laminate QB-AL series	T-110	Imported aluminum base and copper foil, improvement of T-100, enduring highertemperature, higher thermal conductivity
	T-111	Imported aluminum base and copper foil, no-fiberglass, thermal conductivity 1.8~3.0 W/m-k
	T-112	Imported aluminum base and copper foil, no-fiberglass, thermal conductivity 2.5~5.0 W/m-k
	T-113	Imported aluminum base and copper foil, enduring 10min at 300°C, T _g 180°C
	T-114	Imported aluminum base and copper foil, no-fiberglass, enduring 10min at 300°C , Dielectric Constant 3.9
Special base copper clad laminate	T-200	Thick copper clad laminate (4 oz ~ 10 oz)
	T-300	Ferrum base copper clad laminate
	T-400	Stainless steel base copper clad laminate
	T-500	Copper base copper clad laminate
	T-600	Resistance foil clad laminate

STRUCTURE

Circuit Layer

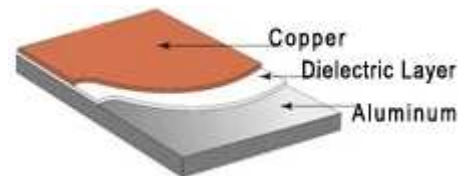
- Copper foil of the gel treatment

Dielectric Layer

- Fiberglass support
- Unsupport

Metal Substrate

- Aluminum, Ferrum, Stainless steel, Copper



Size	Layer	Material	
480mm×580mm 480mm×600mm	Circuit Layer	H oz	18 μ m
		1 oz	35 μ m
		2 oz	70 μ m
		3 oz	100 μ m
		4 oz	137 μ m
		6 oz	206 μ m
		10 oz	343 μ m
	Dielectric Layer	50 μ m、75 μ m、100 μ m、125 μ m、150 μ m	
	Metal Substrate	0.5mm	0.8mm

		1.0mm	1.2mm
		1.5mm	2.0mm
		3.0mm	3.2mm

※ Special demand may be ordered.

Thickness and tolerance

Thickness (mm)		0.80-0.99	1.00-1.19	1.20-1.39	1.40-1.59	1.60-1.99	2.00-2.59	2.60-3.20
Tolerance (mm)	Class 1	± 0.12	± 0.15	±0.17	±0.19	±0.23	±0.25	±0.30
	Class 2	± 0.08	± 0.10	±0.12	±0.14	±0.16	±0.18	±0.20

QB-AL series Aluminum base copper clad laminate

Features:

- Excellent thermal conductivity
- Excellent insulating ability
- Excellent dimensional stability
- Excellent Machinability
- Excellent electromagnetic shielding
- High quality but low price

Applications:

- LED lighting
- Thick film hybrid integrated circuits
- Power supply
- Solid Relay



Performance:

Item	Test condition	Units	Index		
			T-110	T-111	T-112
Thermal Conductibility	A	W/m · k	1.5~2.0	1.8~3.0	2.5~5.0
Peel Strength	A	N/mm	1.5	1.5	1.3
	After thermal stress		1.5	1.5	1.3
Thermal stress	288℃ No-delimitation, No-blistering	S	90S	60S	60S
Surface Resistance	C-96/35/90	MΩ	10 ¹	10 ¹	10 ¹
	E-24/125		10 ¹	10 ⁵	10 ⁵
Volume Resistivity	C-96/35/90	MΩ · cm	10 ⁸	10 ⁸	10 ⁸
	E-24/125		10 ¹	10 ⁵	10 ⁵

Electrical strengthen	A	KV/mm	30	30	30
Flammability	UL94	—	V-0	V-0	V-0
Warping	A	%	0.15	0.15	0.15
Moisture absorption	D-24/23	%	0.05	0.05	0.05
CTI	IEC60112	V	200	175	175

Item	Test condition	Units	Index			
			T-113	T-114		
Thermal Conductibility	A	W/m • k	1.5~2.0	1.5~2.0		
Peel Strength	A After thermal stress	N/mm	1.3	1.3		
			1.3	1.3		
Thermal stress	288°C No-delimitation, No-blistering	S	600S	600S		
Surface Resistance	C-96/35/90	MΩ	10 ^B	10 ^B		
	E-24/125		10 ^B	10 ^B		
Volume Resistivity	C-96/35/90	MΩ • cm	10 ^B	10 ^B		
	E-24/125		10 ^B	10 ^B		
Electrical strengthen	A	KV/mm	30	30		
Flammability	UL94	—	V-0	V-0		
Warping	A	%	0.15	0.15		
Water Absorption	D-24/23	%	0.05	0.05		
CTI	IEC60112	V	—	—		